

S/N 10/823,314

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Neo C. Peng et al.

Examiner: Samuel Heinrich

Serial No.: 10/823,314

Group Art Unit: 3742

Filed: April 13, 2004

Docket No.: 303.772US2

Confirmation No.: 4743

Title: **WAFER DICING DEVICE AND METHOD**

RESPONSE UNDER 37 C.F.R. § 1.116 - EXPEDITED PROCEDURE

Mail Stop RCE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

This paper is responsive to the Advisory Action mailed November 19, 2008.